Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-13 (Canceled)

14. (Currently amended) A method of removing photoresist or residue from a substrate, comprising; applying a composition according to claim ~~1~~ 27 to the substrate at a temperature of from 20°C to 80°C for a period of time sufficient to remove the coating from the substrate.

15. (Original) The method as claimed in claim 14, wherein the temperature is from 20°C to 60°C.

16. (Original) The method as claimed in claim 14, where the temperature is from 20°C to about 40°C.

17. (Original) The method as claimed in claim 14, where the temperature is 20°C.

Claims 18 - 26 (Canceled)

27. (New) A low surface tension, low viscosity composition consisting essentially of:

a. an acidic buffer solution having an acid selected from a carboxylic acid or a polybasic acid and an ammonium salt of the acid in a molar ratio of acid to ammonium salt ranging from 10:1 to 1:10,

b. a polar, organic solvent that is miscible in all proportions in water,

c. a fluoride, and

d. water,

where the aqueous composition has a pH of from about 3 to about 6 and is free of glycols.

28. (New) The composition of claim 27 further consisting essentially of a corrosion inhibitor.

29. (New) The composition of claim 28 wherein the corrosion inhibitor is at least one selected from anthranilic acid, gallic acid, benzoic acid, malonic acid, maleic acid, fumaric acid, D,L-malic acid, isophthalic acid, phthalic acid, maleic anhydride, phthalic anhydride, catechol, pyrogallol, esters of gallic acid, benzotriazole, and mixtures thereof.

30. (New) The composition of claim 28 wherein the corrosion inhibitor has a pKa of less than about 6.

31. (New) The composition of claim 27 wherein the polar solvent is monoethanolamine, n-methylethanolamine, formamide, n-methylformamide, dimethylacetamide, gamma-butyrolactone, N-methylpyrrolidone or mixtures thereof.

32. (New) The composition of claim 27 wherein the fluoride has a composition of the general formula R_1,R_2,R_3,R_4NF, where R_1,R_2,R_3 and R_4 are independently hydrogen, an alcohol group, an alkoxy group, an alkyl group and mixtures thereof.

33. (New) The composition of claim 32 wherein the fluoride is ammonium fluoride, tetramethyl ammonium fluoride, or tetraethyl ammonium fluoride.

34. (New) The composition of claim 27 wherein the fluoride is fluoroboric acid.

35. (New) The composition of claim 27 wherein the acid within the acidic buffer solution comprises acetic acid and wherein the ammonium salt within the acidic buffer solution comprises ammonium acetate.

36. (New) The composition of claim 27 wherein the acid within the acidic buffer solution comprises phosphoric acid and wherein the ammonium salt within the acidic buffer solution comprises an ammonium salt of phosphoric acid.

37. (New) The composition of claim 27 having a surface tension less than or equal to 30 mN/m and a viscosity of less than or equal to 15 centipoise at 25°C.

38. (New) A low surface tension, low viscosity composition consisting essentially of:

a. an acidic buffer solution having acetic acid and ammonium acetate in a molar ratio of acetic acid to ammonium acetate ranging from 10:1 to 1:10,

b. from 30% by weight to 90% by weight of an organic polar solvent that is miscible in all proportion in water,

c. from 0.1% by weight to 20% by weight of a fluoride, and

d. from 0.5% by weight to 40% by weight of water, and

e. optionally up to 15% by weight of a corrosion inhibitor,

wherein a pH of the composition ranges from about 3 to about 6 and the composition is free of glycols.

39. (New) The composition of claim 38 wherein the molar ratio is substantially 1:1.

40. (New) The composition of claim 38 wherein the fluoride comprises ammonium fluoride.

41. (New) The composition of claim 38 wherein the surface tension is less than or equal to 30 mN/m.

42. (New) The composition of claim 38 wherein the viscosity is less than or equal to 15 centipoise at 25°C.

43. (New) A glycol-free composition for cleaning a semiconductor substrate, the composition consisting essentially of:

a. an acidic buffer solution having an acid selected from a carboxylic acid and a polybasic acid and an ammonium salt of the acid in a molar ratio of acid to ammonium salt ranging from 10:1 to 1:10 and wherein the acidic buffer solution is present in an amount sufficient to maintain a pH of the composition from about 3 to about 6,

b. from 30% by weight to 90% by weight of an organic polar solvent that is miscible in all proportion in water,

c. from 0.1% by weight to 20% by weight of a fluoride,

d. from 0.5% by weight to 40% by weight of water, and

e. optionally up to 15% by weight of a corrosion inhibitor.

44. (New) The composition of claim 43 wherein the acid is acetic acid.

45. (New) The composition of claim 43 wherein the ammonium salt is ammonium acetate.

46. (New) The composition of claim 43 wherein the molar ratio is substantially 1:1.